# 2.0X1.2X0.6 (mm) WiFi/Bluetooth Ceramic Chip Antenna (YF20121) Engineering Specification

#### 1. Product Number

YF	2012	H2	Р	2G45	00
1	2	3	4	5	6



(1)Product Type	Chip Antenna
(2)Size Code	2.0x1.2mm
(3)Type Code	H2
(4)Packing	Paper &Reel
(5)Frequency	2.45GHz
(6)Internal code	<b>0</b> 0



# 深圳市迎丰天线技术有限公司

SHEN ZHEN YINGFENG ANTENNA TECHNOLOGYCO.,LTD

Prepared by : JIEXI Designed by : Jason Checked by : Jason Approved by : MR.FANG

TITLE: 2.0 x 1.2 x 0.6(mm) WiFi/Bluetooth Ceramic Chip
Antenna (YF2012-1) Engineering Specification

DOCUMENT
NO.

YF2012H2P2G4500
D

Address: Room 412, Building 7, Phase II, Nanshan Yungu Entrepreneurship Park, No. 2 Pingshan 1st Road, Pingshan Community, Taoyuan Street, Nanshan District, Shenzhen

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#### 2. Features

- \*Stable and reliable in performances
- \*Low temperature coefficient of frequency
- \*Low profile, compact size
- \*RoHS compliance
- \*SMT processes compatible

#### 3. Applications

- \*Bluetooth earphone systems
- \*Hand-held devices when WiFi /Bluetooth functions are needed, e.g., Smart phone.
- \*IEEE802.11 b/g/n
- \*ZigBee
- \*Wireless PCMCIA cards or USB dongle

#### 4. Description

Yingfeng chip antenna series are specially designed for WiFi/Bluetooth applications. Based on yingfeng proprietary design and processes, this chip antenna has excellent stability and sensitivity to consistently provide high signal reception efficiency.

#### 5. Electrical Specifications (80 x 40 mm<sup>2</sup> ground plane)

#### 5-1. Electrical Table

Characteristics		Specifications	Unit
Outline Dimensions		2.0x1.2x0.6	mm
Working Frequency		2400~2500	MHz
VSWR		2 Max.	
Impedance		50	Ω
Polarization		Linear Polarization	
Coin	Peak	2.5 (typical)	dBi
Gain	Efficiency	75 (typical)	%



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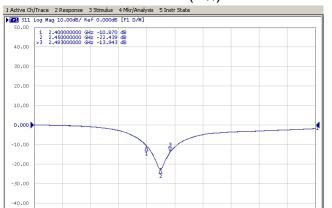
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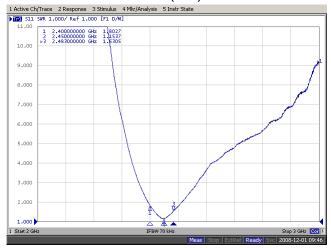
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#### 5-2. Return Loss & VSWR

Return Loss (S<sub>11</sub>)

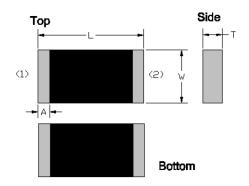


#### VSWR(S<sub>11</sub>)



#### 6. Antenna Dimensions & Test Board (unit: mm)

a. Antenna Dimensions



Dimension (mm)						
L	L 2.05+-0.15					
W	1.20+-0.15					
Т	0.50+-0.10					
Α	0.20+-0.10					

No.	Terminal Name
1	Feeding/GNG
2	GND/Feeding

P.S: Top & down and left & right side are symmetrical, No direction



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#### b. Test Board with Antenna

Unit: mm





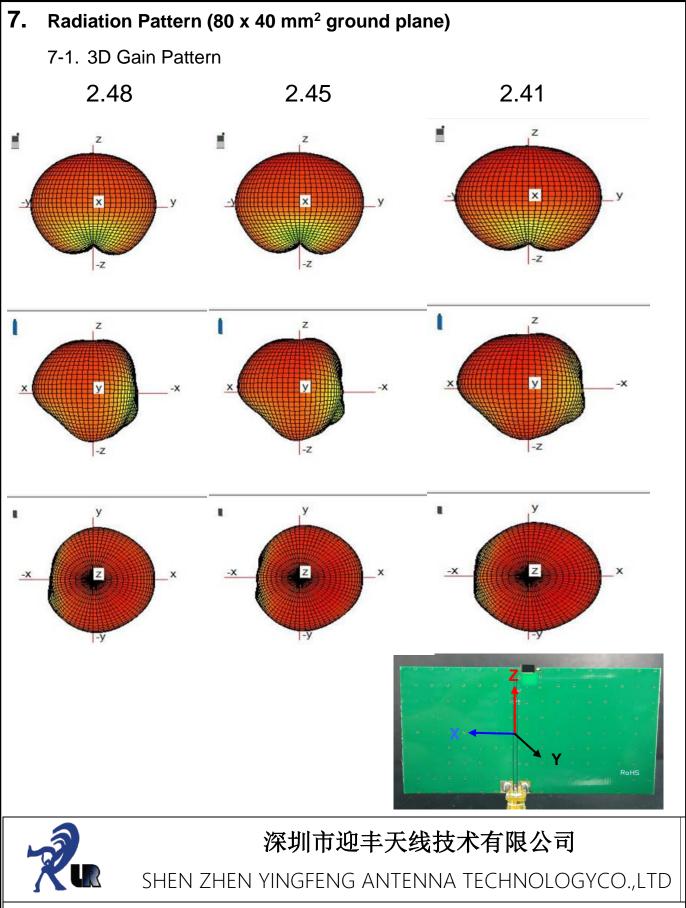
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Antenna (YF2012-1) Engineering Specification NO. D OF PAGE 4 12



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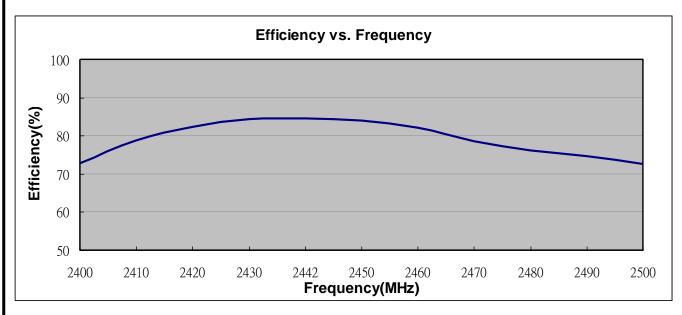
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#### 7-2. 3D Efficiency Table

Frequency( MHz)	2400	2410	2420	2430	2442	2450	2460	2470	2480	2490	2500
Efficiency (dB)	-1.4	-1.0	-0.9	-0.7	-0.7	-0.8	-0.9	-1.1	-1.2	-1.3	-1.4
Efficiency (%)	72.8	73.7	74.3	74.4	75.5	75.0	74.0	73.6	73.1	72.6	71.5
Gain (dBi)	2.1	2.2	2.3	2.4	2.5	2.5	2.4	1.8	1.7	1.6	1.4

#### 7-3. 3D Efficiency vs. Frequency



#### 8. Layout Guide

a. Solder Land Pattern:

Land pattern for soldering (gray marking areas) is as shown below. Depending on Customer's requirement, matching circuit as shown below is also recommended.



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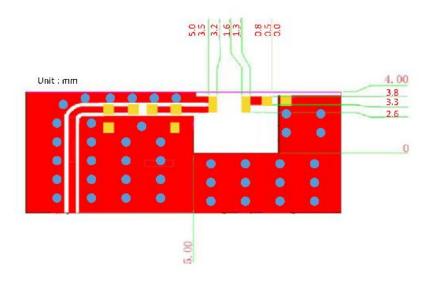
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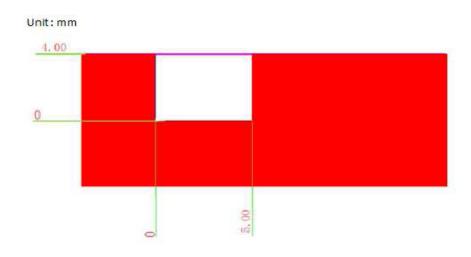
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#### 2). PCB Top View:

Type1:





**Bottom View** 



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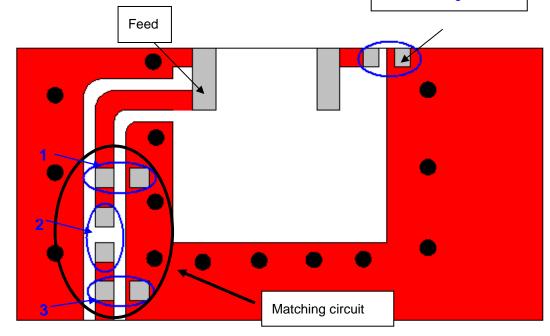
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Unit: mm

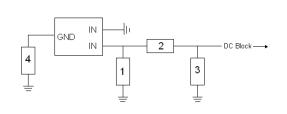
## 9. Frequency tuning

a. Chip antenna tuning scenario:

4. Fine tuning elemet



b. Matching circuit: (Center frequency is about 2442 MHz @ 80 x 40 mm² ground plane)



Antenna (YF2012-1) Engineering Specification

S	System Matching Circuit Component						
Location	Description	Vendor	Toleranc e				
1	1.2 pF*	Murata (0402)	±0.1 pF				
2	10PF*	Murata(0402)	±0.5 PF				
3	N/A*	-	-				
Fine tuning element 4	1.5 pF*	Murata (0402)	±0.1 pF				

<sup>\*</sup>Typical reference values which may need to be changed when circuit boards or part vendors are different.

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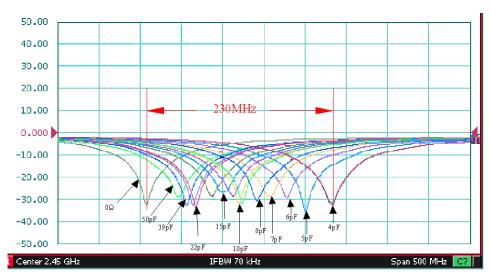
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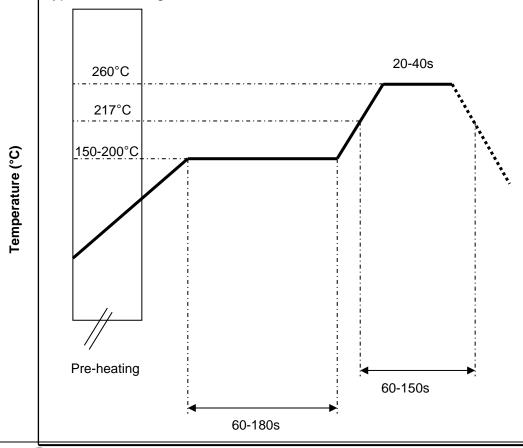
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c. Fine tuning element vs. Center frequency

## 10. Soldering Conditions



a. ↑Typical Soldering Profile for Lead-free Proces





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# 11. Packing

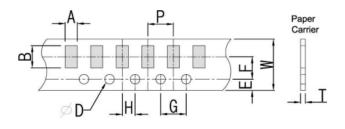
(1) Quantity/Reel: 5000 pcs/Reel

(2) Plastic tape:

# 

TYPE	SI	ZE	Α	φB	φC	φD	w	φM	
2012	7"	5K/Reel	2.0±0.5	13.5±1.0	21±1.0	60±1.0	11.5±2.0	178±2.0	

#### **Tapping Specification**



P	Packaging	Type	Α	В	w	E	F	G	Н	T	øD	P
P	aper Type	2012	1.90+0.20	3.50±0.20	8.0+0.20	1.75±0.10	3.5±0.05	4.0+0.10	2.0+0.05	0.75+0.10	+0.10 1.50	4.0±0.1
											-0	



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# Reliability Table

Test Item	Procedure	Requirements Ceramic Type	Remark (Reference)	
Electrical Characterization		Fulfill the electrical specification	User Spec.	
Thermal Shock	1. Preconditioning:  50 ± 10 °C / 1 hr , then keep for 24 ± 1 hrs at room temp.  2. Initial measure: Spec: refer Initial spec.  3. Rapid change of temperature test:  -30 °C to +85 °C; 100 cycles;  15 minutes at Lower category temperature;  15 minutes at Upper category temperature.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 107	
Temperature Cycling	1. Initial measure: Spec: refer Initial spec. 2. 100 Cycles (-30°C to +85°C), Soak Mode=1 (2 Cycle/hours). 3. Measurement at 24 ± 2Hours after test condition.	No Visible Damage. Fulfill the electrical specification.	JESD22 JA104	
Vibration	5g's for 20 min., 12 cycles each of 3 orientations  Note: Use 8"X5" PCB .031" thick 7 secure points on, one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10-2000 Hz.	No Visible Damage.	MIL-STD-202 Method 204	
Mechanical Shock	Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks) Peak value: 1,500g's Duration: 0.5ms Velocity change: 15.4 ft/s Waveform: Half-sine	No Visible Damage.	MIL-STD-202 Method 213	
Humidity Bias	1. Humidity. 85% R.H., Temperature: 85 ± 2 °C. 2. Time: 500 ± 24 hours. 3. Measurement at 24 ± 2hrs after test condition.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 Method 106	
Resistance	Preheating time: 1~2 min.	ηο γισιοίο σαιπάχο.	4.10	



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Solder temperature: 260 ± 5°C.

Dipping time: 5 ± 0.5s

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Board	1. Mounting method:	No Visible Damage.	AEC-Q200
Flex	IR-Reflow. PCB Size (L:100 × W:40 × T:1.6mm)		005
(SMD)	2. Apply the load in direction of the arrow until bending reaches		
	2 mm. Support Solder Chip Printed circuit board before testing		
	45+2		
	Probe to exert banding force  Radius 340  Printed caput board under test  Displacement		
Adhesion	Force of 1.8Kg for 60 seconds.	No Visible Damage	AEC-Q200
	radius 0.5 mm	Magnification of 20X or	006
	1.	greater may be employed for inspection of the	
	DUT	mechanical integrity of the	
		device body terminals and	
		body/terminal junction.	
	thickness		
	eubetrate XIII		
	press tool		
	shear force		
Physical	Any applicable method using x10 magnification, micrometers,	In accordance with	JESD22
Dimension	calipers, gauges, contour projectors, or other measuring	specification.	JB100
	equipment, capable of determining the actual specimen dimensions.		



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